

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT4578286

<b>SUBMISSION TYPE:</b>	CORRECTIVE ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	Corrective Assignment to correct the NAME OF THE 7TH ASSIGNOR FROM I-AN HUANG TO "YI-AN HUANG" previously recorded on Reel 041716 Frame 0754. Assignor(s) hereby confirms the ASSIGNMENT OF ASSIGNORS INTEREST.
<b>RESUBMIT DOCUMENT ID:</b>	504484436

## CONVEYING PARTY DATA

Name	Execution Date
PIN-HONG CHEN	03/17/2017
TSUN-MIN CHENG	03/17/2017
CHIH-CHIEH TSAI	03/17/2017
TZU-CHIEH CHEN	03/17/2017
KAI-JIUN CHANG	03/17/2017
CHIA-CHEN WU	03/17/2017
YI-AN HUANG	07/13/2017
YI-WEI CHEN	03/17/2017

## RECEIVING PARTY DATA

<b>Name:</b>	UNITED MICROELECTRONICS CORP.
<b>Street Address:</b>	No.3, Li-Hsin Road 2, Science-Based Industrial Park
<b>City:</b>	Hsin-Chu City
<b>State/Country:</b>	TAIWAN
<b>Name:</b>	FUJIAN JINHUA INTEGRATED CIRCUIT CO., LTD.
<b>Street Address:</b>	6TH FLOOR, PODIUM OF ELECTRIC POWER COMPANY BUILDING, MEILING STREET, JINJIANG CITY
<b>City:</b>	QUANZHOU CITY, FUJIAN PROVINCE
<b>State/Country:</b>	CHINA

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15468084

## CORRESPONDENCE DATA

Fax Number: (703)997-4517

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

PATENT

**Correspondent Name:** WINSTON HSU  
**Address Line 1:** 5F., NO.389, FUHE RD., YONGHE DIST.,  
**Address Line 4:** NEW TAIPEI CITY, TAIWAN

**ATTORNEY DOCKET NUMBER:** NAUP2959USA

**NAME OF SUBMITTER:** SIBYL YU

**SIGNATURE:** /SIBYL YU/

**DATE SIGNED:** 09/04/2017

**Total Attachments: 19**

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## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

## CONVEYING PARTY DATA

Name	Execution Date
Pin-Hong Chen	03/17/2017
Tsun-Min Cheng	03/17/2017
Chih-Chieh Tsai	03/17/2017
Tzu-Chieh Chen	03/17/2017
Kai-Jiun Chang	03/17/2017
Chia-Chen Wu	03/17/2017
I-An Huang	03/17/2017
Yi-Wei Chen	03/17/2017

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ATTORNEY DOCKET NUMBER:	NAUP2959USA
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NAME OF SUBMITTER:	SIBYL YU
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Signature:	/SIBYL YU/
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Date:	03/23/2017
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Total Attachments: 16

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RECEIPT INFORMATION

EPAS ID: PAT4334500  
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**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION  
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

**Title of Invention:**

**SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME**

As the below named inventor, I hereby declare that:  
This declaration is directed to:

- The attached application, or  
 United States application number \_\_\_\_\_ filed on \_\_\_\_\_, or  
 PCT international application number \_\_\_\_\_ filed on \_\_\_\_\_

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS** having a postal address of **CORP.**

**No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.**

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

In consideration of the payment by **Fujian Jinhua Integrated Circuit** having a postal address of **Co., Ltd.**

**6th floor, Podium of electric power company building, Meiling street, Jinjiang city, Quanzhou City, Fujian province 362200, P.R.C.**

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I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WINTNESS WHEREOF, I have hereunto set hand and seal this MAR 17 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Pin-Hong Chen

Date: MAR 17 2017

Signature: Pin-Hong Chen

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Tsun-Min Cheng

Date: MAR 17 2017

Signature: Tsun-Min Cheng

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chih-Chieh Tsai**

Date: **MAR 1 7 2017**

Signature: Chih-Chieh Tsai

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Tzu-Chieh Chen

Date: MAR 17 2017

Signature: Tzu-Chieh Chen

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Kai-Jiun Chang**

Date: MAR 17 2017

Signature:

Kai-Jiun Chang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chia-Chen Wu

Date: MAR 17 2017

Signature: Chia-Chen Wu

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*Yi-An Huang July 13 2017*

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: ~~I-An Huang~~ Yi-An Huang

Date: MAR 17 2017

Signature: *I-An Huang*

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In consideration of the payment by **Fujian Jinhua Integrated Circuit Co., Ltd.** having a postal address of \_\_\_\_\_

**6th floor, Podium of electric power company building, Meiling street, Jinjiang city, Quanzhou City, Fujian province 362200, P.R.C.**

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WINTNESS WHEREOF, I have hereunto set hand and seal this MAR 17 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yi-Wei Chen

Date: MAR 17 2017

Signature: Yi-Wei Chen